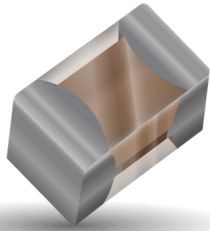


RC Equalizer Network



GENERAL DESCRIPTION

These ruggedly constructed, ultraminiature (EIA 0402, 1005 metric) equalizers combine high-performance tantalum nitride (TaN) resistive elements and silicon/oxygen/nitrogen (SiON) capacitive elements with KYOCERA AVX's proprietary, automotive-qualified, glass-sandwich FLEXITERM[®] surface-mount technology, which provides an extra measure of protection against flexure damage during installation. The new GEQ Series equalizers are also manufactured with 100% laser trimming to achieve tight tolerances and offer a low 0.5mm profile, a 125mW power rating, resistance values spanning 10–50Ω, and capacitance values extending from 1–50pF.

Rated for a wide range of operating temperatures (-55°C to +125°C) and compliant with RoHS, ideal applications for the series extend across the optoelectronic, telecommunications, broadband, military, electronic warfare, space, test, and instrumentation markets and include optical transceiver modules, broadband receivers, and transmission and receiver optical subassemblies (TOSA and ROSA).

FEATURES

- EIA 0402 Case Size
- Resistance Range: 10 to 50 Ω typ.
- Capacitance Range: 1 to 50 pF typ.
- Parallel Configurations
- Power Rating: 125 mW
- Operating Temperature: -55°C to +125°C
- Laser Trimmed Resistors
- RoHS Compliant

APPLICATIONS

- Optical Transceiver Modules
- Broadband Receiver
- TOSA / ROSA

MARKETS

- Opto-electronics
- Telecom
- Broadband Jamming for EW
- Military
- Instrumentation and Test

*For other RC Combinations and EIA Sizes contact factory

[CLICK HERE TO DOWNLOAD DATA FILES](#)

HOW TO ORDER

RCN

Series
0402

25R0

Resistance Value (Ω)

3 significant digits
R = decimal point

F

Resistance Tolerance

F = 1%

05R0

Capacitance Value (pF)

3 significant digits
R = decimal point

J

Capacitance Tolerance

J* = 5%
K* = 10%
M* = 20%
*Minimum tolerance = +/- 0.1pF

T

Terminations

T = NiSn Plated

TR

Packaging

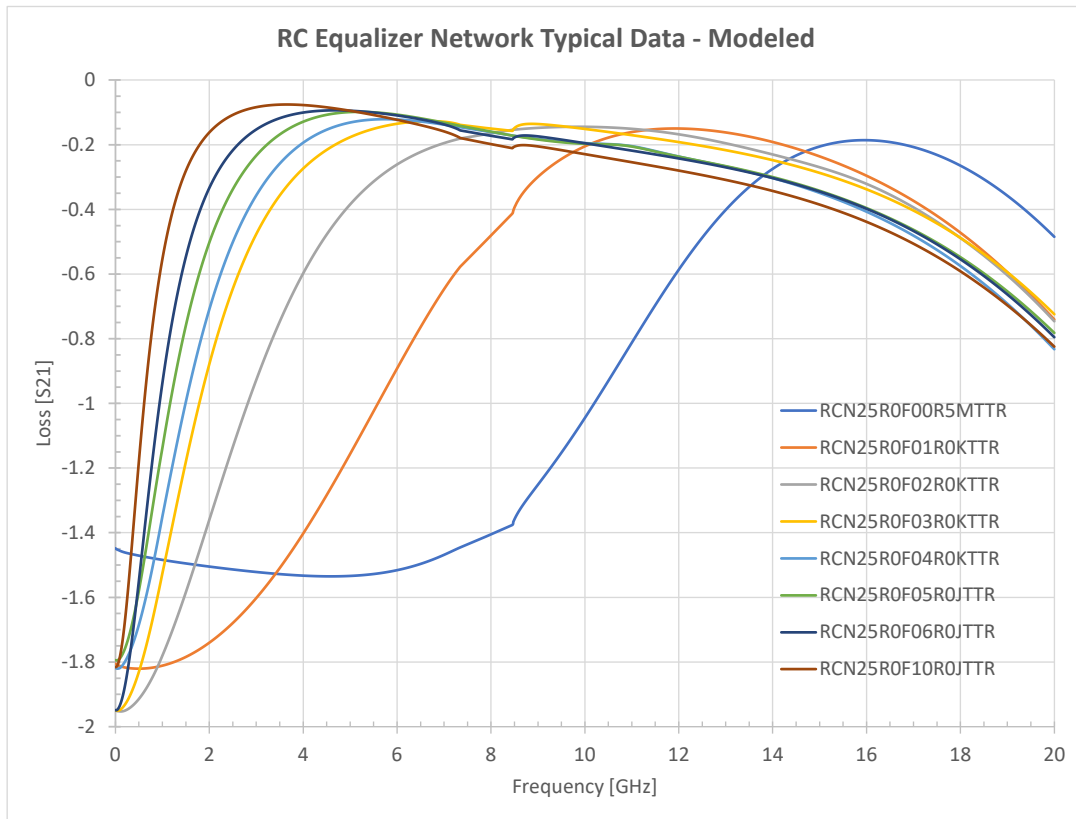
TR = Tape & Reel



EQUALIZER GAIN SLOPE TABLE

Part Number	Starting Frequency (Typical) (GHz)	Loss at Starting Frequency (Typical) (dB)	End Frequency (Typical) (GHz)	Loss at End Frequency (Typical) (dB)	Bandwidth (Typical) (GHz)	Gain (Typical) (dB)
RCN09R0F12R5JTTR	0	-0.7	4	-0.05	4	0.65
RCN25R0F00R5MTTR	5	-1.5	16	-0.2	11	1.3
RCN25R0F01R0KTTR	0	-1.8	12	-0.15	12	1.65
RCN25R0F02R0KTTR	0	-1.8	10	-0.15	10	1.65
RCN25R0F03R0KTTR	0	-1.8	7	-0.15	7	1.65
RCN25R0F04R0KTTR	0	-1.8	6	-0.15	6	1.65
RCN25R0F05R0JTTR	0	-1.8	5	-0.15	5	1.65
RCN25R0F06R0JTTR	0	-1.8	4.5	-0.15	4.5	1.65
RCN25R0F10R0JTTR	0	-1.8	3.5	-0.15	3.5	1.65
RCN30R0F0R33MTTR	9.25	-2.9	16	-0.3	6.75	2.6
RCN43R0F1R15KTTR	0	-3	9	-0.15	9	2.85
RCN50R0F0R31MTTR	6	-3.3	16	-0.3	10	3

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SPECIFICATIONS

Package Size: EIA 0402

Design: Glass wafer sandwich

Termination: NiSn plated

Power Rating: 125 mW

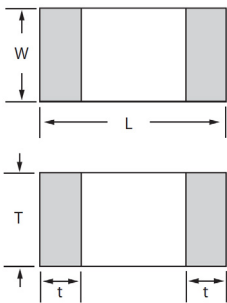
Operating Temperature Range: -55°C to +125°C

Tolerance: Resistor: 1-5%, **Capacitor:** 5-20%

Resistance Range: 10 to 50 Ω (typical)

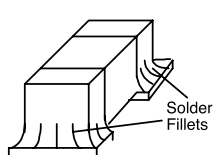
Capacitance Range: 1 to 50 pF (typical)

DIMENSIONS



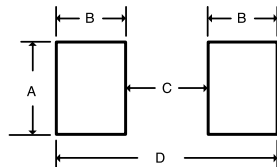
Size (EIA)	Length (L)	Width (W)	Thickness (T)	Termination (t)
0402	1.02 ± 0.051 (0.040 ± 0.002)	0.51 ± 0.051 (0.020 ± 0.002)	0.50 ± 0.10 (.020 ± 0.004)	0.25 ± 0.051 (0.010 ± 0.002)

SUGGESTED MOUNTING PAD DIMENSIONS



Normal Pads

W = Chip Width L = Chip Length T = Chip Thickness



Case Size	A Min.	B Min.	C Min.	D Min.
0402	0.0213	0.0125	0.0206	0.0436

Dimensions are in inches.

RESISTOR MATERIAL

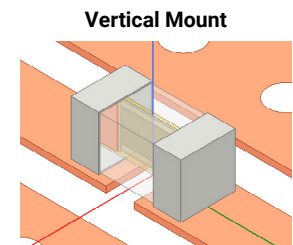
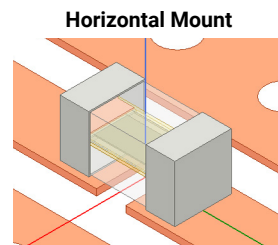
Thin Film Resistors	TaN
Typical Sheet Resistivity (ohm/sq)	10 to 100
TCR (ppm/°C, -25 to 125°C)	-100 to -150
Stability (Change after 1000 hours @ 125°C)	1.0%

CAPACITOR MATERIAL

Material	SiON
pF/mm Typical	50 to 100
BDV (v/μm)	600
DF	≤0.1%
TCC (ppm/°C, -25 to 125°C)	±60

ENVIRONMENTAL TESTS

Reliability Test	Criteria
Life Test	1000 Hrs. @ 125°C @ 50 mW
85/85 Temp./ Humidity Breakdown	1080 Hrs. @ 50 mW
Thermal Cycle	100 cycles @ -40 to 125°C
Termination Strength	200 g for 50 seconds (Dage Tester)x



NOTES:

Mounting will allow the solder fillet to travel up approximately 0.015" of the chip's end and side termination surface. Heavier fillets require a predeposition of solder paste and or an increase in pad dimensions. Typical solder paste application is a .008" to 0.01" thickness with >50% of volume in solder alloy. Can be mounted in both vertical and horizontal orientation without changing electrical performance

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POWER DERATING

